



Embedded Systems Week

www.esweek.org

September 28 – October 3, 2025

Taipei, Taiwan



Call for Papers

2025 International Conference on Embedded Software (EMSOFT)

September 28 – October 3, 2025, Taipei, Taiwan

EMSOFT (*ACM SIGBED International Conference on Embedded Software*) aims at advancing the science and engineering of **embedded software**. Since 2001, EMSOFT has been at the forefront of embedded software innovation, connecting academia, industry, and government. At EMSOFT, cutting-edge research meets practical application in designing and analyzing software that brings the digital and physical worlds together. EMSOFT's tradition is at the heart of *cyber-physical and embedded systems*, where computation, networking, and physical dynamics converge.

Journal Track:

Abstract Submission: March 23, 2025

Full Paper Submission: March 30, 2025 (firm)

Notification of Acceptance: July 13, 2025

Late Breaking and Work-in-Progress Tracks:

Paper Submission: June 1, 2025 (firm)

Notification of Acceptance: July 13, 2025

All submissions are due by midnight, AOE.

We invite submissions on all aspects of embedded software systems, including but not limited to:

- **Embedded distributed, networked systems**
 - Time-critical embedded systems
 - Multi-/many-core processors, hardware accelerators
 - Embedded operating systems and middleware
 - Scheduling, resource allocation, and execution time analysis
 - QoS management and performance analysis
 - Hardware and software co-design
- **Embedded software design and analysis**
 - Energy-efficient embedded software
 - Safety/Mixed-critical embedded software
 - Software design and analysis for cyber-physical systems
 - Embedded software architectures for data-intensive applications and signal processing
- **Cyber-security, safety, resilience and fault-tolerance**
 - Embedded software security and privacy
 - Embedded software safety
 - Robust implementation of control systems

- **Processes and methods**

- Formal modeling and verification
- Testing, validation, and certification
- Model- and component-based approaches
- Empirical studies and their reproduction
- Sustainability and energy optimization
- Application areas including automotive, avionics, energy, health care, mobile devices, multimedia, machine learning, and autonomous systems

Submitted manuscripts must be **double blind**. Authors should not reveal their identity directly or indirectly (e.g., through references). The submitted work must be **original**, not formerly published or under review elsewhere.

The EMSOFT 2025 journal track will follow a **two-stage review** process. Authors of papers that pass the first review stage will revise their work based on the received comments, within a short time frame (around two weeks). Papers accepted at the second stage will appear in ACM TECS (see below).

Journal-Integrated Publication Model: All full papers accepted in EMSOFT'25 will be published in **ACM Transactions on Embedded Computing Systems (TECS)**. All late-breaking papers accepted in one of the three conferences will be published in **IEEE Embedded Systems Letters (ESL)**.

See details at <https://esweek.org/author-information>

ESWEEK General Chairs:

Tei-Wei Kuo, National Taiwan University, Taiwan

Andy Pimentel, University of Amsterdam, Netherlands

EMSOFT Program Chairs:

Martina Maggio, Saarland University, Germany

Borzoo Bonakdarpour, Michigan State University, USA